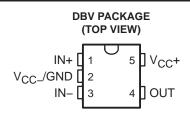
SLOS250G - JUNE 1999 - REVISED JANUARY 2005

- Wide Range of Supply Voltages, Single Supply 3 V to 30 V, or Dual Supplies
- Class AB Output Stage
- True Differential-Input Stage
- Low Input Bias Current
- Internal Frequency Compensation
- Short-Circuit Protection



description/ordering information

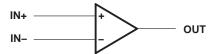
The TL343 is a single operational amplifier similar in performance to the μ A741, but with several distinct advantages. It is designed to operate from a single supply over a range of voltages from 3 V to 30 V. Operation from split supplies also is possible, provided the difference between the two supplies is 3 V to 30 V. The common-mode input range includes the negative supply. Output range is from the negative supply to $V_{CC} - 1.5$ V.

ORDERING INFORMATION

TA	V _{IO} MAX AT 25°C	PACKAG	_{GE} †	ORDERABLE PART NUMBER	TOP-SIDE MARKING‡
4000 1- 40500	40>/	00T 00 F (DD) ()	Reel of 3000	TL343IDBVR	T41
-40°C to 125°C	10 mV	SOT-23-5 (DBV)	Reel of 250	TL343IDBVT	T4I_

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

symbol



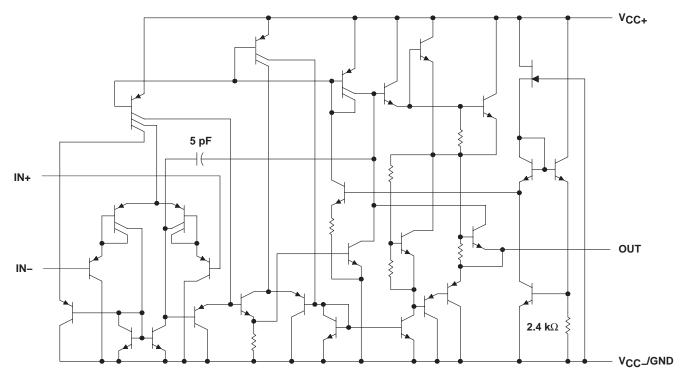


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[‡]The actual top-side marking has one additional character that designates the assembly/test site.

schematic



NOTE A: Component values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

		MAX	UNIT
Complexed to a Constitute (A)	CC+	18	.,
Supply voltage (see Note 1)	CC-	-18	V
Supply voltage, V _{CC+} with respect to V _{CC-}		36	V
Differential input voltage (see Note 2)		±36	V
Input voltage (see Notes 1 and 3)		±18	V
Package thermal impedance, θ _{JA} (see Notes 4 and 5)		206	°C/W
Operating virtual junction temperature, T _J		150	°C
Storage temperature range, T _{stg}		-65 to 150	°C

- NOTES: 1. These voltage values are with respect to the midpoint between V_{CC+} and V_{CC-}.
 - 2. Differential voltages are at IN+ with respect to IN-.

 - Neither input must ever be more positive than V_{CC+} or more negative than V_{CC-}.
 Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_J(max) T_A)/θ_{JA}. Selecting the maximum of 150°C can affect reliability.
 - 5. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions

		MIN	MAX	UNIT
VCC	Single-supply voltage	3	30	V
V _{CC+}	Dead and the second sec	1.5	15	.,
VCC-	Dual-supply voltage	-1.5	-15	V
TA	Operating free-air temperature	-40	125	°C

electrical characteristics at specified free-air temperature, $V_{CC\pm}$ = ±15 V (unless otherwise noted)

PARAMETER		TE	ST CONDITIONS		MIN	TYP	MAX	UNIT
.,	land effect with an	On a Nata O		25°C		2	10	>/
VIO	Input offset voltage	See Note 6		Full range			12	mV
$\alpha_{V_{IO}}$	Temperature coefficient of input offset voltage	See Note 6		Full range		10		μV/°C
1	land offers comment	Con Note C		25°C		30	50	A
lio	Input offset current	See Note 6		Full range			200	nA
α _{IIO}	Temperature coefficient of input offset current	See Note 6		Full range		50		pA/°C
1				25°C		-200	-500	A
l _{IB}	Input bias current	See Note 6	Full range			-800	nA	
VICR	Common-mode input voltage range [‡]			25°C	V _{CC} - to 13	V _{CC} - to 13.5		V
		R _L = 10 kΩ		25°C	±12	±13.5		
Vом	Peak output-voltage swing	$R_L = 2 k\Omega$		25°C	±10	±13		V
				Full range	±10			
Δ	Large-signal differential	V- 140 V	D. 010	25°C	20	200		V/mV
AVD	voltage amplification	$V_0 = \pm 10 \text{ V},$	$R_L = 2 k\Omega$	Full range	15			V/mV
ВОМ	Maximum-output-swing bandwidth	V _{OPP} = 20 V, THD ≤ 5%,	$A_{VD} = 1$, $R_L = 2 k\Omega$	25°C		9		kHz
B ₁	Unity-gain bandwidth	$V_O = 50 \text{ mV},$	$R_L = 10 \text{ k}\Omega$	25°C		1		MHz
φm	Phase margin	C _L = 200 pF,	$R_L = 2 k\Omega$	25°C		44		Deg
rį	Input resistance	f = 20 Hz		25°C	0.3	1		$M\Omega$
r _O	Output resistance	f = 20 Hz		25°C		75		Ω
CMRR	Common-mode rejection ratio	V _{IC} = V _{ICR} (min	n)	25°C	70	90		dB
kSVS	Supply-voltage sensitivity ($\Delta V_{IO}/\Delta V_{CC}$)	$V_{CC\pm} = \pm 2.5 \text{ to}$	±15 V	25°C		30	150	μV/V
los	Short-circuit output current§			25°C	±10	±30	±55	mA
Icc	Total supply current	No load,	See Note 6	25°C		0.7	2.8	mA

[†] All characteristics are measured under open-loop conditions, with zero common-mode voltage, unless otherwise specified. Full range for T_A is -40°C to 125°C.

NOTE 6: V_{IO} , I_{IO} , I_{IB} , and I_{CC} are defined at $V_{O} = 0$.



 $[\]ddagger$ The V_{ICR} limits are linked directly, volt-for-volt, to supply voltage; the positive limit is 2 V less than V_{CC+}.

[§] Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.

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electrical characteristics, V_{CC+} = 3 V and 5 V, V_{CC-} = 0 V, T_A = 25°C (unless otherwise noted)

	PARAMETER	TEST CONDITIONS†	MIN	TYP	MAX	UNIT
VIO	Input offset voltage	V _O = 1.5 V and 2.5 V		2	10	mV
IIO	Input offset current	V _O = 1.5 V and 2.5 V		30	50	nA
I _{IB}	Input bias current	V _O = 1.5 V and 2.5 V		-200	-500	nA
VOM	Peak output voltage swing‡	$R_L = 10 \text{ k}\Omega$	3.3	3.5		V
AVD	Large-signal differential voltage amplification	$V_O = 1.7 \text{ V to } 3.3 \text{ V}, \qquad R_L = 2 \text{ k}\Omega$	20	200		V/mV
ksvs	Supply-voltage sensitivity ($\Delta V_{IO}/\Delta V_{CC\pm}$)	$V_{CC\pm} = \pm 2.5 \text{ V to } \pm 15 \text{ V}$			150	μV/V
ICC	Supply current	V _O = 1.5 V and 2.5 V, No load		0.7	1.75	mA

TAll characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified.

operating characteristics, $V_{CC\pm}$ = ± 15 V, T_A = 25°C, A_{VD} = 1 (unless otherwise noted)

	PARAMETER			TYP	UNIT		
SR	Slew rate at unity gain	$V_{I} = \pm 10 \text{ V},$	C _L = 100 pF,	$R_L = 2 k\Omega$,	See Figure 1	1	V/μs
t _r	Rise time	$\Delta V_{O} = 50 \text{ mV},$	$C_L = 100 pF$,	$R_L = 10 \text{ k}\Omega$,	See Figure 1	0.35	μs
t _f Fall time		$\Delta V_{O} = 50 \text{ mV},$	$C_L = 100 pF$,	$R_L = 10 \text{ k}\Omega$,	See Figure 1	0.35	μs
	Overshoot factor	$\Delta V_O = 50 \text{ mV},$	C _L = 100 pF,	$R_L = 10 \text{ k}\Omega$,	See Figure 1	20%	
	Crossover distortion	$V_{I(PP)} = 30 \text{ mV},$	V _{OPP} = 2 V,	f = 10 kHz		1%	

PARAMETER MEASUREMENT INFORMATION

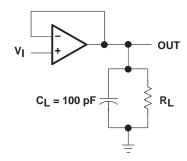
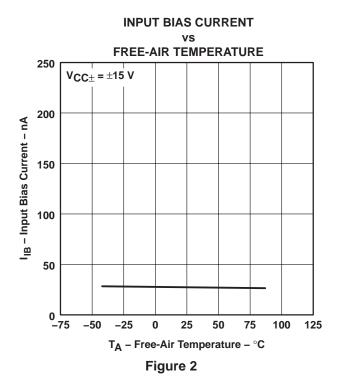
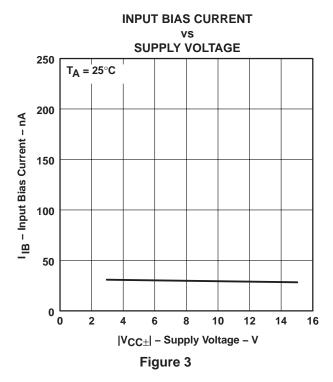


Figure 1. Unity-Gain Amplifier

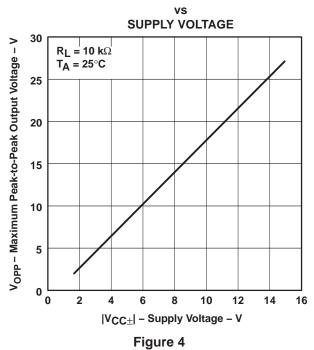
[‡] Output swings essentially to ground.

TYPICAL CHARACTERISTICS[†]

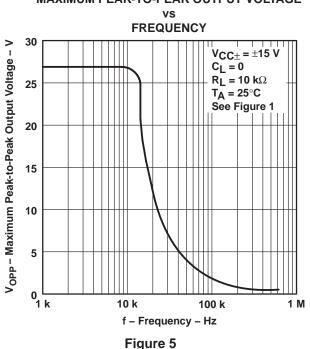




MAXIMUM PEAK-TO-PEAK OUTPUT VOLTAGE



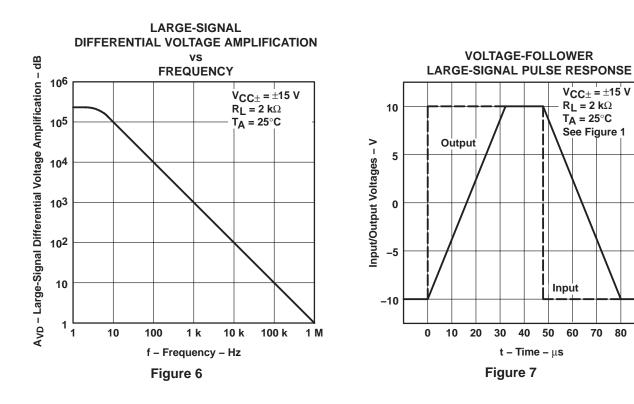
MAXIMUM PEAK-TO-PEAK OUTPUT VOLTAGE



[†] Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.



TYPICAL CHARACTERISTICS[†]



80

[†] Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.





PACKAGE OPTION ADDENDUM

1-Nov-2017

PACKAGING INFORMATION

www.ti.com

Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
TL343IDBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 125	(T4IG, T4IL, T4IS)	Samples
TL343IDBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 125	(T4IG, T4IL, T4IU)	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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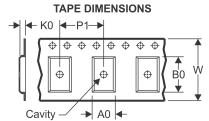
1-Nov-2017

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Aug-2017

TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

All difficusions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL343IDBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TL343IDBVR	SOT-23	DBV	5	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
TL343IDBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3

www.ti.com 3-Aug-2017



*All dimensions are nominal

1								
	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
	TL343IDBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
	TL343IDBVR	SOT-23	DBV	5	3000	202.0	201.0	28.0
	TL343IDBVT	SOT-23	DBV	5	250	180.0	180.0	18.0

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